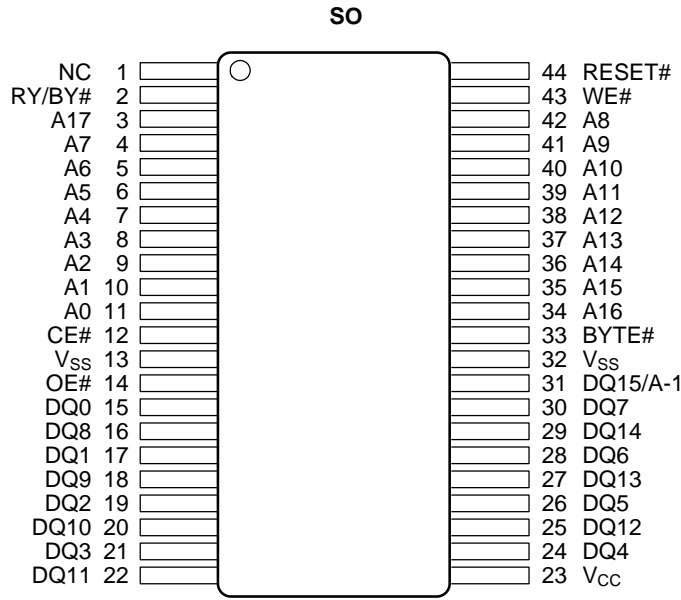


CONNECTION DIAGRAMS

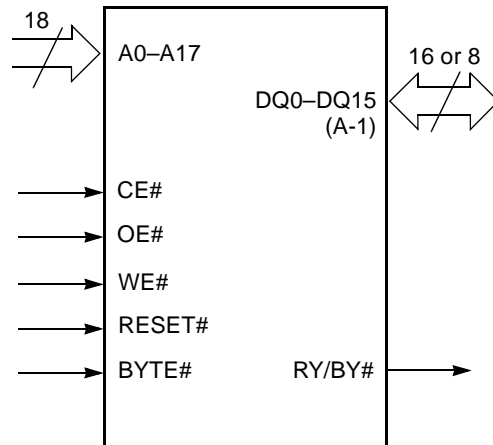


21505C-3

PIN CONFIGURATION

- A0–A17 = 18 addresses
- DQ0–DQ14 = 15 data inputs/outputs
- DQ15/A-1 = DQ15 (data input/output, word mode),
A-1 (LSB address input, byte mode)
- BYTE# = Selects 8-bit or 16-bit mode
- CE# = Chip enable
- OE# = Output enable
- WE# = Write enable
- RESET# = Hardware reset pin, active low
- RY/BY# = Ready/Busy# output
- V_{CC} = +5.0 V single power supply
(see Product Selector Guide for
device speed ratings and voltage
supply tolerances)
- V_{SS} = Device ground
- NC = Pin not connected internally

LOGIC SYMBOL

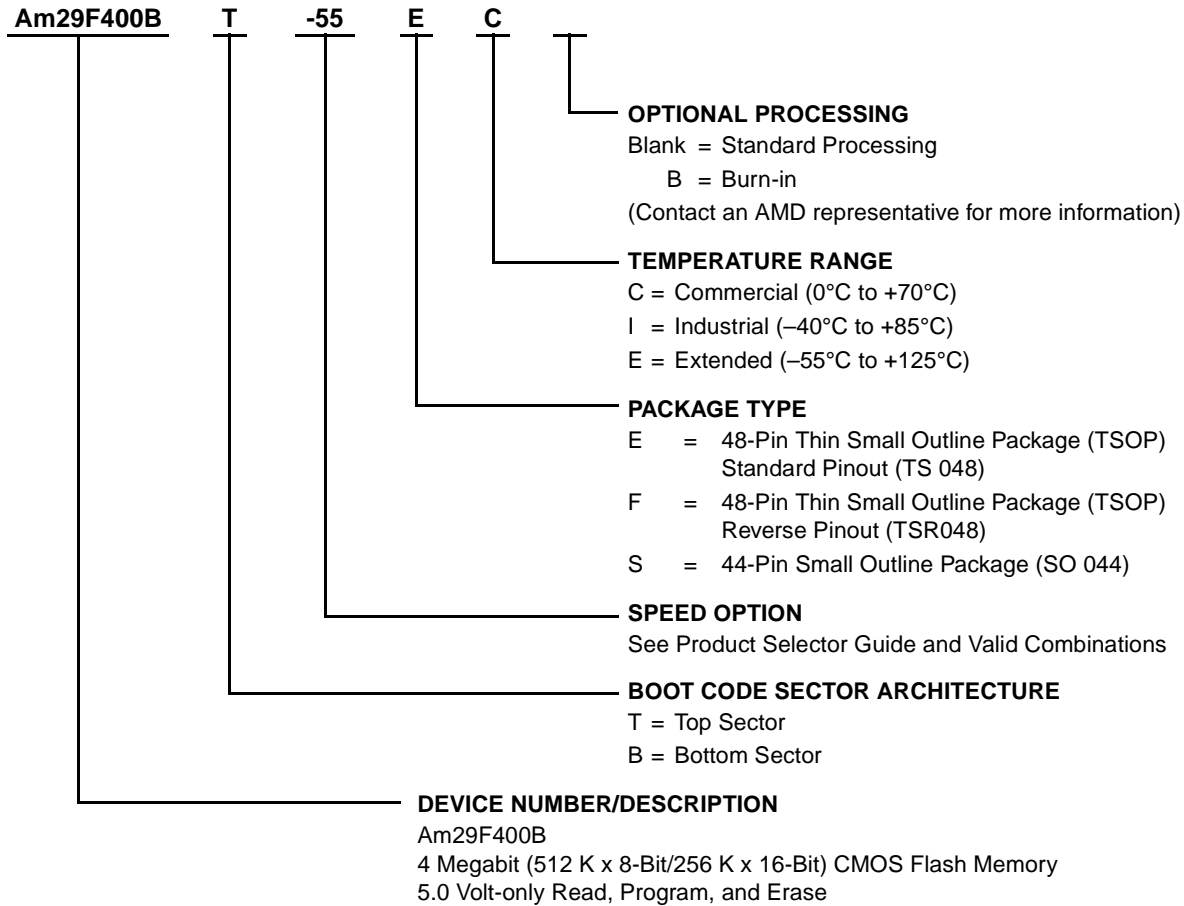


21505C-4

ORDERING INFORMATION

Standard Products

AMD standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of the elements below.



Valid Combinations	
Am29F400BT-55, Am29F400BB-55	EC, EI, FC, FI, SC, SI
Am29F400BT-60, Am29F400BB-60	EC, EI, EE, FC, FI, FE, SC, SI, SE
Am29F400BT-70, Am29F400BB-70	
Am29F400BT-90, Am29F400BB-90	
Am29F400BT-120, Am29F400BB-120	
Am29F400BT-150, Am29F400BB-150	

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations and to check on newly released combinations.

DEVICE BUS OPERATIONS

This section describes the requirements and use of the device bus operations, which are initiated through the internal command register. The command register itself does not occupy any addressable memory location. The register is composed of latches that store the commands, along with the address and data information needed to execute the command. The contents of

the register serve as inputs to the internal state machine. The state machine outputs dictate the function of the device. Table 1 lists the device bus operations, the inputs and control levels they require, and the resulting output. The following subsections describe each of these operations in further detail.

Table 1. Am29F400B Device Bus Operations

Operation	CE#	OE#	WE#	RESET#	A0–A17	DQ0–DQ7	DQ8–DQ15	
							BYTE# = V _{IH}	BYTE# = V _{IL}
Read	L	L	H	H	A _{IN}	D _{OUT}	D _{OUT}	High-Z
Write	L	H	L	H	A _{IN}	D _{IN}	D _{IN}	High-Z
CMOS Standby	V _{CC} ± 0.5 V	X	X	V _{CC} ± 0.5 V	X	High-Z	High-Z	High-Z
TTL Standby	H	X	X	H	X	High-Z	High-Z	High-Z
Output Disable	L	H	H	H	X	High-Z	High-Z	High-Z
Hardware Reset	X	X	X	L	X	High-Z	High-Z	High-Z
Temporary Sector Unprotect (See Note)	X	X	X	V _{ID}	A _{IN}	D _{IN}	D _{IN}	High-Z

Legend:

L = Logic Low = V_{IL}, H = Logic High = V_{IH}, V_{ID} = 12.0 ± 0.5 V, X = Don't Care, D_{IN} = Data In, D_{OUT} = Data Out, A_{IN} = Address In

Note: See the sections on Sector Protection and Temporary Sector Unprotect for more information.

Word/Byte Configuration

The BYTE# pin controls whether the device data I/O pins DQ15–DQ0 operate in the byte or word configuration. If the BYTE# pin is set at logic '1', the device is in word configuration, DQ15–DQ0 are active and controlled by CE# and OE#.

If the BYTE# pin is set at logic '0', the device is in byte configuration, and only data I/O pins DQ0–DQ7 are active and controlled by CE# and OE#. The data I/O pins DQ8–DQ14 are tri-stated, and the DQ15 pin is used as an input for the LSB (A-1) address function.

Requirements for Reading Array Data

To read array data from the outputs, the system must drive the CE# and OE# pins to V_{IL}. CE# is the power control and selects the device. OE# is the output control and gates array data to the output pins. WE# should remain at V_{IH}. The BYTE# pin determines whether the device outputs array data in words or bytes.

The internal state machine is set for reading array data upon device power-up, or after a hardware reset. This ensures that no spurious alteration of the memory content occurs during the power transition. No command is necessary in this mode to obtain array data. Standard microprocessor read cycles that assert valid addresses on the device address inputs produce valid data on the

device data outputs. The device remains enabled for read access until the command register contents are altered.

See “Reading Array Data” for more information. Refer to the AC Read Operations table for timing specifications and to Figure 9 for the timing diagram. I_{CC1} in the DC Characteristics table represents the active current specification for reading array data.

Writing Commands/Command Sequences

To write a command or command sequence (which includes programming data to the device and erasing sectors of memory), the system must drive WE# and CE# to V_{IL}, and OE# to V_{IH}.

For program operations, the BYTE# pin determines whether the device accepts program data in bytes or words. Refer to “Word/Byte Configuration” for more information.

An erase operation can erase one sector, multiple sectors, or the entire device. Tables 2 and 3 indicate the address space that each sector occupies. A “sector address” consists of the address bits required to uniquely select a sector. The “Command Definitions” section has details on erasing a sector or the entire chip, or suspending/resuming the erase operation.

After the system writes the autoselect command sequence, the device enters the autoselect mode. The system can then read autoselect codes from the internal register (which is separate from the memory array) on DQ7–DQ0. Standard read cycle timings apply in this mode. Refer to the “Autoselect Mode” and “Autoselect Command Sequence” sections for more information.

I_{CC2} in the DC Characteristics table represents the active current specification for the write mode. The “AC Characteristics” section contains timing specification tables and timing diagrams for write operations.

Program and Erase Operation Status

During an erase or program operation, the system may check the status of the operation by reading the status bits on DQ7–DQ0. Standard read cycle timings and I_{CC} read specifications apply. Refer to “Write Operation Status” for more information, and to “AC Characteristics” for timing diagrams.

Standby Mode

When the system is not reading or writing to the device, it can place the device in the standby mode. In this mode, current consumption is greatly reduced, and the outputs are placed in the high impedance state, independent of the OE# input.

The device enters the CMOS standby mode when the CE# and RESET# pins are both held at $V_{CC} \pm 0.5$ V. (Note that this is a more restricted voltage range than V_{IH} .) The device enters the TTL standby mode when CE# and RESET# pins are both held at V_{IH} . The device requires standard access time (t_{CE}) for read access when the device is in either of these standby modes, before it is ready to read data.

The device also enters the standby mode when the RESET# pin is driven low. Refer to the next section, “RESET#: Hardware Reset Pin”.

If the device is deselected during erasure or programming, the device draws active current until the operation is completed.

In the CMOS and TTL/NMOS-compatible DC Characteristics tables, I_{CC3} represents the standby current specification.

RESET#: Hardware Reset Pin

The RESET# pin provides a hardware method of resetting the device to reading array data. When the RESET# pin is driven low for at least a period of t_{RP} , the device **immediately terminates** any operation in progress, tristates all output pins, and ignores all read/write commands for the duration of the RESET# pulse. The device also resets the internal state machine to reading array data. The operation that was interrupted should be reinitiated once the device is ready to accept another command sequence, to ensure data integrity.

Current is reduced for the duration of the RESET# pulse. When RESET# is held at V_{IL} , the device enters the TTL standby mode; if RESET# is held at $V_{SS} \pm 0.5$ V, the device enters the CMOS standby mode.

The RESET# pin may be tied to the system reset circuitry. A system reset would thus also reset the Flash memory, enabling the system to read the boot-up firmware from the Flash memory.

If RESET# is asserted during a program or erase operation, the RY/BY# pin remains a “0” (busy) until the internal reset operation is complete, which requires a time of t_{READY} (during Embedded Algorithms). The system can thus monitor RY/BY# to determine whether the reset operation is complete. If RESET# is asserted when a program or erase operation is not executing (RY/BY# pin is “1”), the reset operation is completed within a time of t_{READY} (not during Embedded Algorithms). The system can read data t_{RH} after the RESET# pin returns to V_{IH} .

Refer to the AC Characteristics tables for RESET# parameters and to Figure 10 for the timing diagram.

Output Disable Mode

When the OE# input is at V_{IH} , output from the device is disabled. The output pins are placed in the high impedance state.

Table 2. Am29F400BT Top Boot Block Sector Address Table

Sector	A17	A16	A15	A14	A13	A12	Sector Size (Kbytes/ Kwords)	Address Range (in hexadecimal)	
								(x8) Address Range	(x16) Address Range
SA0	0	0	0	X	X	X	64/32	00000h–0FFFFh	00000h–07FFFh
SA1	0	0	1	X	X	X	64/32	10000h–1FFFFh	08000h–0FFFFh
SA2	0	1	0	X	X	X	64/32	20000h–2FFFFh	10000h–17FFFh
SA3	0	1	1	X	X	X	64/32	30000h–3FFFFh	18000h–1FFFFh
SA4	1	0	0	X	X	X	64/32	40000h–4FFFFh	20000h–27FFFh
SA5	1	0	1	X	X	X	64/32	50000h–5FFFFh	28000h–2FFFFh
SA6	1	1	0	X	X	X	64/32	60000h–6FFFFh	30000h–37FFFh
SA7	1	1	1	0	X	X	32/16	70000h–77FFFh	38000h–3BFFFh
SA8	1	1	1	1	0	0	8/4	78000h–79FFFh	3C000h–3CFFFh
SA9	1	1	1	1	0	1	8/4	7A000h–7BFFFh	3D000h–3DFFFh
SA10	1	1	1	1	1	X	16/8	7C000h–7FFFFh	3E000h–3FFFFh

Table 3. Am29F400BB Bottom Boot Block Sector Address Table

Sector	A17	A16	A15	A14	A13	A12	Sector Size (Kbytes/ Kwords)	Address Range (in hexadecimal)	
								(x8) Address Range	(x16) Address Range
SA0	0	0	0	0	0	X	16/8	00000h–03FFFh	00000h–01FFFh
SA1	0	0	0	0	1	0	8/4	04000h–05FFFh	02000h–02FFFh
SA2	0	0	0	0	1	1	8/4	06000h–07FFFh	03000h–03FFFh
SA3	0	0	0	1	X	X	32/16	08000h–0FFFFh	04000h–07FFFh
SA4	0	0	1	X	X	X	64/32	10000h–1FFFFh	08000h–0FFFFh
SA5	0	1	0	X	X	X	64/32	20000h–2FFFFh	10000h–17FFFh
SA6	0	1	1	X	X	X	64/32	30000h–3FFFFh	18000h–1FFFFh
SA7	1	0	0	X	X	X	64/32	40000h–4FFFFh	20000h–27FFFh
SA8	1	0	1	X	X	X	64/32	50000h–5FFFFh	28000h–2FFFFh
SA9	1	1	0	X	X	X	64/32	60000h–6FFFFh	30000h–37FFFh
SA10	1	1	1	X	X	X	64/32	70000h–7FFFFh	38000h–3FFFFh

Note:

Address range is A17:A-1 in byte mode and A17:A0 in word mode. See “Word/Byte Configuration” section for more information.

Autoselect Mode

The autoselect mode provides manufacturer and device identification, and sector protection verification, through identifier codes output on DQ7–DQ0. This mode is primarily intended for programming equipment to automatically match a device to be programmed with its corresponding programming algorithm. However, the autoselect codes can also be accessed in-system through the command register.

When using programming equipment, the autoselect mode requires V_{ID} (11.5 V to 12.5 V) on address pin A9. Address pins A6, A1, and A0 must be as shown in Table 4. In addition, when verifying sector protection,

the sector address must appear on the appropriate highest order address bits (see Tables 2 and 3). Table 4 shows the remaining address bits that are don't care. When all necessary bits have been set as required, the programming equipment may then read the corresponding identifier code on DQ7–DQ0.

To access the autoselect codes in-system, the host system can issue the autoselect command via the command register, as shown in Table 5. This method does not require V_{ID} . See “Command Definitions” for details on using the autoselect mode.